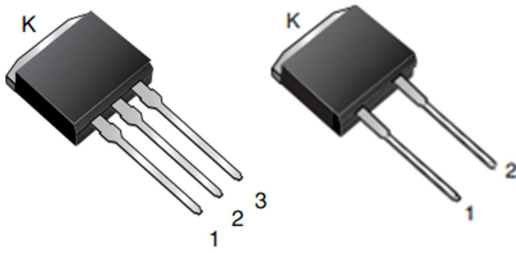


1: Certification

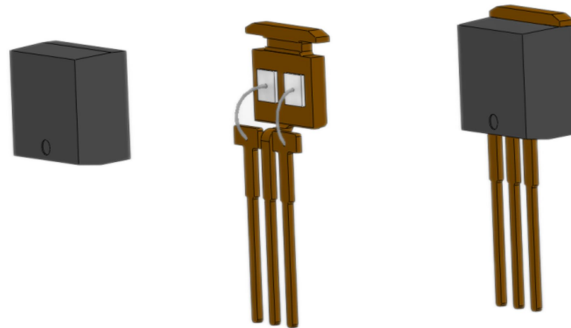
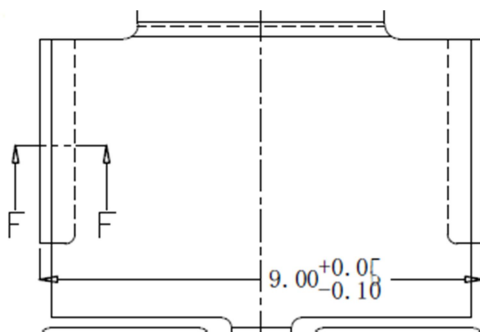
- System:
 - IATF 16949
 - ISO9001
 - ISO14001
 - ISO45001
- ROHS/REACH/ELV:
 - Lead frame、Wire, Molding compound、Post plating.
- UL 94: V-0
- Whisker Test: JESD 201 class 1A
- AEC-Q101 (Rev E): Qualified Available
- Solder bath temperature : 275°C maximum, 10 s



TO-262AB

TO-262AC

2: Internal Structure Diagram



Meet Die Size

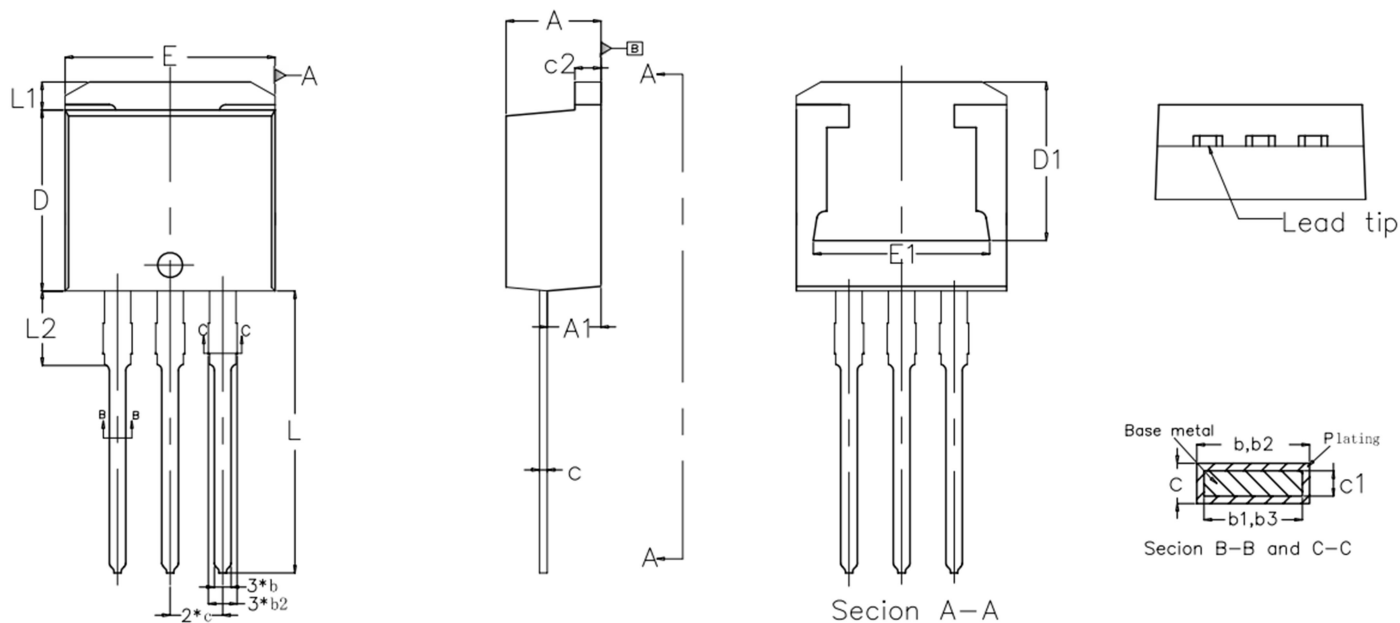
Die Pad(mm)	Die size(mm)	
X=8.50, Y=5.65	Double die (Max)	Single die(Max)
	X=3.50, Y=5.30	X=7.50, Y=5.30

3: Reliability Experiment

	Test	Test Condition
1	Temperature Cycle (TMCL)	500 cycles at -55°C to 150°C
2	Unbiased Highly Accelerated Stress Test (UHST)	96 hours at Ta = 130°C, RH = 85% ;P=2.27atm.
3	High Temperature, Humidity & Reverse Bias (THBS)	1000 hours at Tj = 85°C, RH = 85%, Reverse Bias = 80% rated voltage
4	Thermal Fatigue (TFAT)	10000 cycles, Tj = 25°C to 125°C, DTj ≥ 80°C, Id=depends on device & Ton = Toff ~2.5 to 3.5 mins.
5	Static High Temperature Life (SHTL)	1000 hours – Tj = max operating temp, Reverse Bias = 80% / 100% rated voltage.(according to customer request).
6	High Temperature Storage (HTSL)	1000 hours at Ta = 150°C or Ta=175°C

4: Package Outline Dimensions in millimeters

4.1 POD



SYMBOL	MILLIMETERS			NOTES		SYMBOL	MILLIMETERS			NOTES
	Normal	MIN.	MAX.				Normal	MIN.	MAX.	
A	4.55	4.44	4.70			D1	7.75	7.50	8.00	
A1	2.60	2.54	2.79			E	10.18	10.00	10.40	
b	0.85	0.7	0.9			E1	8.57	8.25	8.80	
b1	0.83	0.51	0.89			e	2.54	2.54BSC		
b2	1.33	1.20	1.45			L	13.55	13.46	14.00	
b3	1.33	1.20	1.45			L1	1.35	1.00	1.65	
c	0.50	0.38	0.56			L2	3.60	3.56	3.71	
c1	0.48	0.38	0.56							
c2	1.27	1.14	1.40							
D	8.75	8.51	8.89							